BRCS1C0P06MF

Rev.B Aug.-2024

DATA SHEET

/ Descriptions

SOT23-6 P

P- CHANNEL MOSFET in a SOT23 -6 Plastic Package.

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V_{DS}=-60V; I_D=-3A

$R_{DS(on)1}$@-10V ≤ 100mΩ (Type.83mΩ)

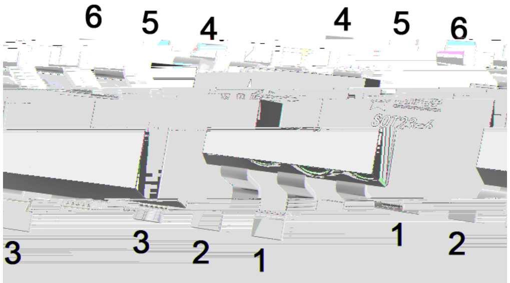
$R_{DS(on)2}$@-4.5V ≤ 130mΩ (Type.100mΩ)

HF Product.

PWM

PWM application & Load switch.

/ Equivalent Circuit



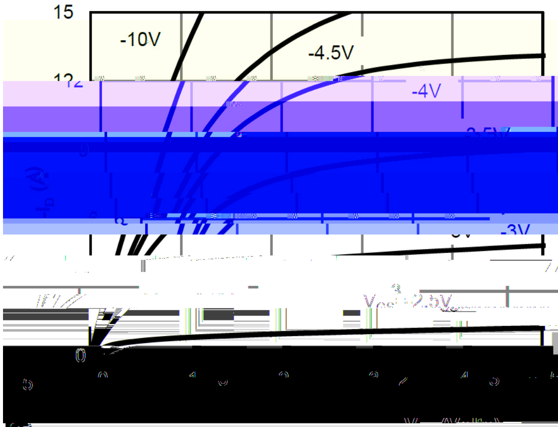
PIN1 D PIN 2 D PIN 3 G PIN 4 S PIN 5 D PIN 6 D

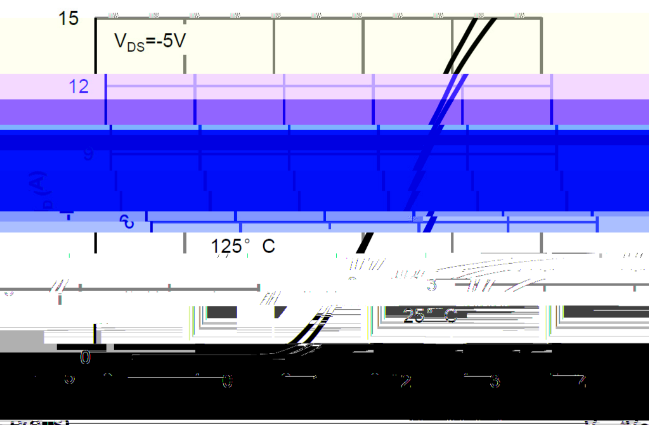
/ Marking

See Marking Instructions.

Parameter	Symbol	Rating	Unit
Drain–Source Voltage	V_{DSS}	-60	V
Gate–Body Leakage Voltage	V_{GSS}	±20	V
Drain Current – Continuous	I_D	-3	A
Pulsed Drain Current	I_{DM}	-16	A
Power Dissipation	P_D	1.4	W

/ Electrical Characteristic Curve





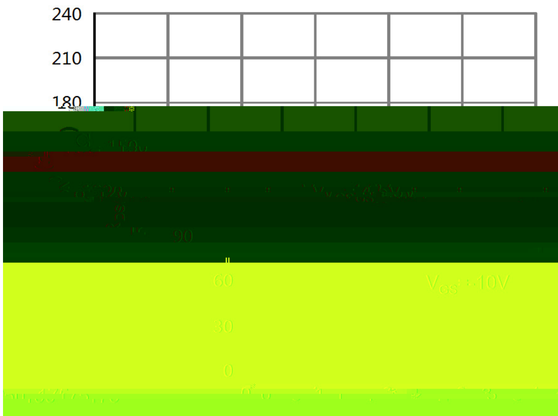
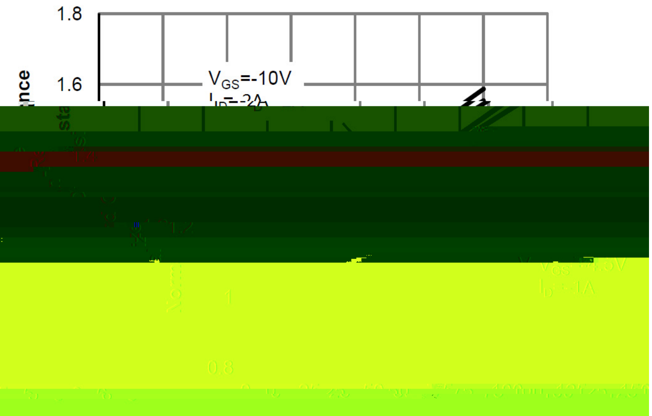


Figure 3: On-Resistance vs. Drain Current and Gate Voltage



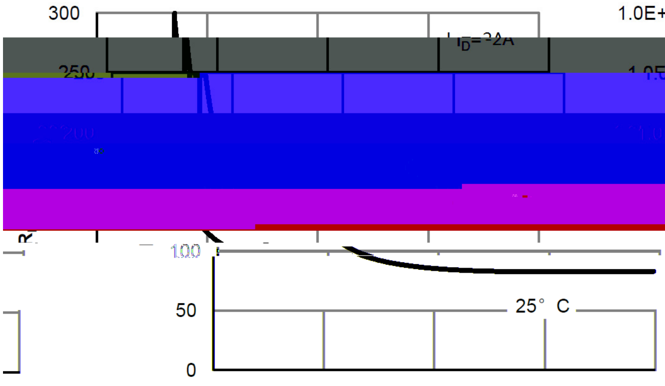


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Figure 5: On-Resistance vs. Gate-Source Voltage

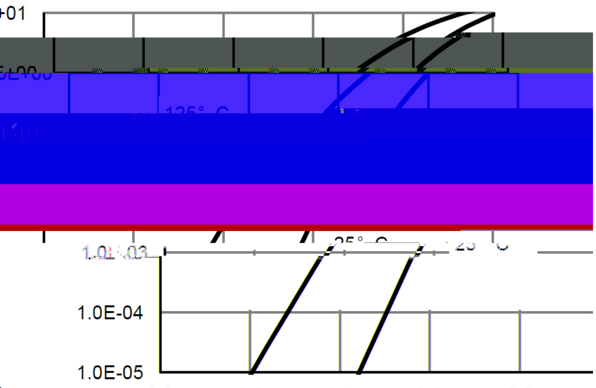


Figure 6: Body-Diode Characte

/ Electrical Characteristic Curve

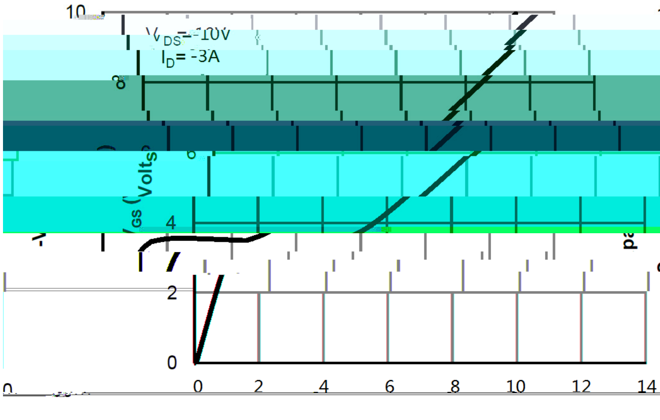


Figure 7: Gate-Charge Characteristics

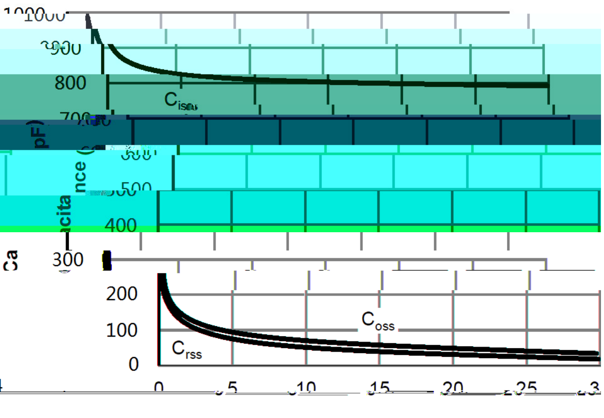
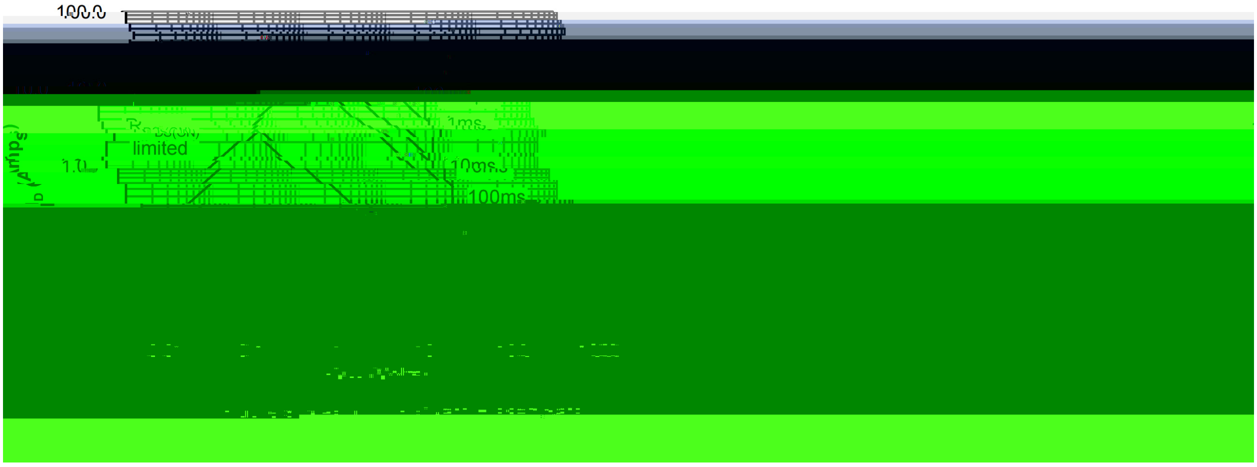
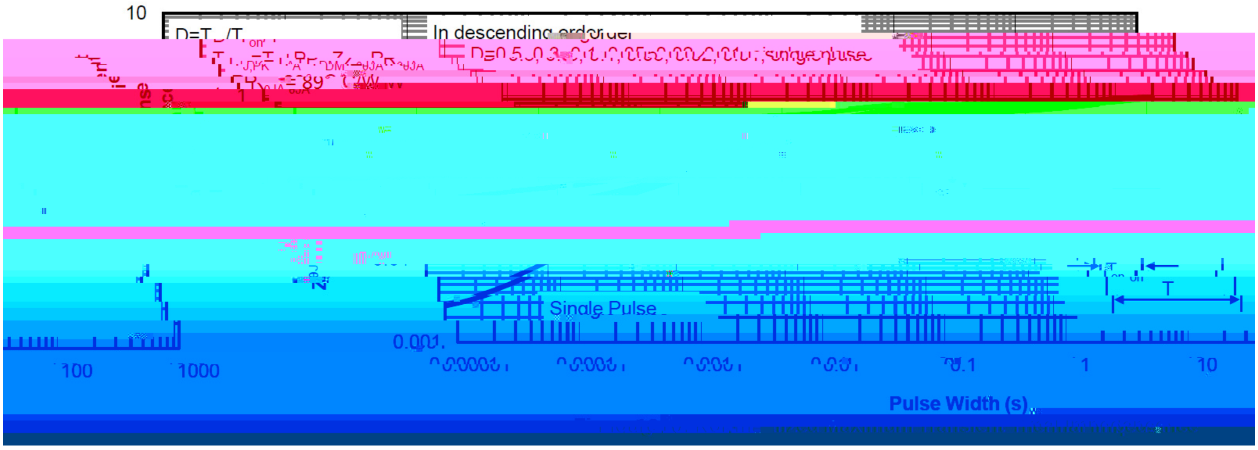


Figure 8: Capacitance Characteristics

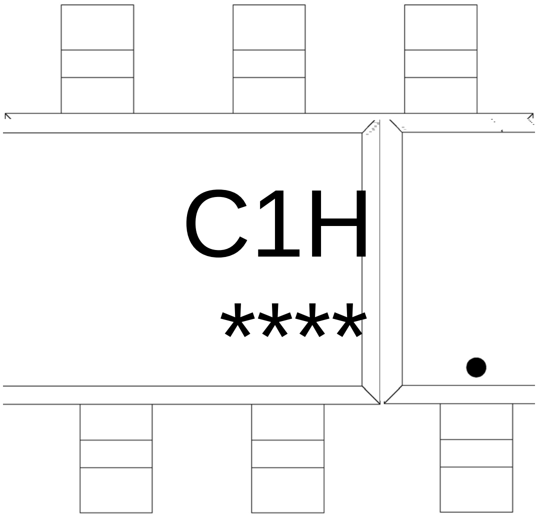




/ Package Dimensions

[redacted]

/ Marking Instructions



C1:

H

****:

Note:

C1: Product Type Code

H: Company Code

**** Lot No. Code, code change with Lot No.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

1 150 180 60 90sec;
2 245±5 5±0.5sec;
3 2 10 /sec.

1.Preheating:150~180 , Time:60~90sec.
2.Peak Temp.:245±5 , Duration:5±0.5sec.
3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units	Dimension (unit mm^3)